



Additional Information







Samples

Resources Accessories

Agency Approvals

Agency	Agency File Number
<i>71</i> 2	E230531

Maximum Ratings and Thermal Characteristics

(T_A=25 °C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Peak Pulse Power Dissipation at	8/20µs (Note 2)	D	1200	W
$T_A = 25^{\circ}C$ (Note 1)	10/1000µs (Note 3)	P _{PPM}	200	W
Thermal Resistance	$R_{\theta JA}$	220	$^{\circ}\text{C/W}$	
Thermal Resistance	$R_{\theta JL}$	100	°C/W	
Operating Tempera	T _J	-55 to 150	°C	
Storage Temperatur	T _{STG}	-55 to 150	°C	

Notes:

1. Non-repetitive current pulse, per Fig. 4 and derated above T_J (initial) =25°C per Fig. 3.

Description

SMF3.3 is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

Features and Benefits

- 200W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycle): 0.01%
- 1200W peak pulse power capability at 8/20us waveform
- Excellent clamping capability
- Compatible with industrial standard package SOD-123FL
- Low profile: maximum height of 1.08mm.
- For surface mounted applications to optimize board space
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC 61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2

- EFT protection of data lines in accordance with IEC 61000-4-4
- Fast response time: typically less than 1.0ns from 0 Volts to VBR min
- High temperature soldering: 260°C/30 seconds at terminals
- Built-in strain relief
- Meet MSL level1, per J-STD-020C, LF maximun peak of 260°C
- Matte tin lead–free plated
- Halogen-free and RoHScompliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

Applications

SMF3.3 series is ideal for the protection of portable electronics/ hard drives, notebooks, VCC busses, POS terminal, SSDs, power supplies, monitors, and vulnerable circuit used in other consumer applications.

Functional Diagram



Electrical Characteristics (T_A=25°C unless otherwise noted)

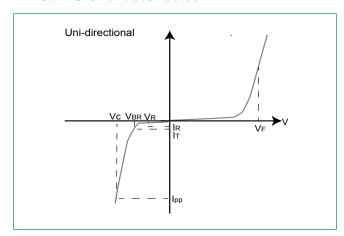
Part Number	Voltage	ge V _{BR}	Test Current I _T	Reverse Stand off Voltage V _R	Maximum Reverse Leakage @ V _R	Maximum Peak Pulse Current (10/1000µS)	Maximum Clamping Voltage @I _{pp} (10/1000uS)	Maximum Peak Pulse Current (8/20uS)	Maximum Clamping Voltage @I _{pp} (8/20uS)	
		MIN	MAX	(mA)	(V)	I _R (μA)	I _{pp} (A)	V _c (V)	I _{pp} (A)	V _c (V)
SMF3.3	33	3.4	4.3	10	3.3	0.5	30.0	6.8	120.0	10.0

Notes

- 1. V_{BR} measured after I_{T} applied for 300 μ s, I_{T} = sequare wave pulse or equivalent.
- 2. Surge current waveform per 10/1000µs exponential wave and derated per Fig.2.
- 3. All terms and symbols are consistent with ANSI/IEEE C62.35.
- 4. Surge current waveform per 8/20µs exponential wave and derated per Fig.6



I-V Curve Characteristics



- P_{PPM} Peak Pulse Power Dissipation Max power dissipation
- $\mathbf{V}_{\text{\tiny R}}$ **Stand-off Voltage** -- Maximum voltage that can be applied to the TVS without operation
- $m \emph{V}_{BR}$ Breakdown Voltage Maximum voltage that flows though the TVS at a specified test current (IT)
- V_c Clamping Voltage Peak voltage measured across the TVS at a specified lppm (peak impulse current)
- I. Reverse Leakage Current Current measured at VR
- V, Forward Voltage Drop for Uni-directional

Note: VF distribution range from 7V to 16V at IF 1mA.

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1 -TVS Transients Clamping Waveform

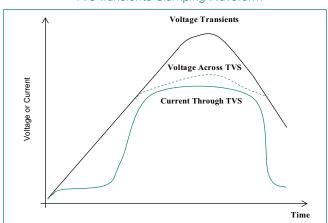


Figure 2 -Peak Pulse Power Rating Curve

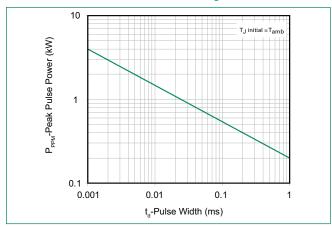


Figure 3 Peak Pulse Power Derating Curve

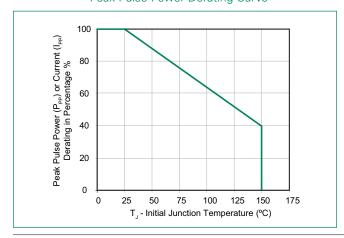


Figure 4 - 10/1000µS Pulse Waveform

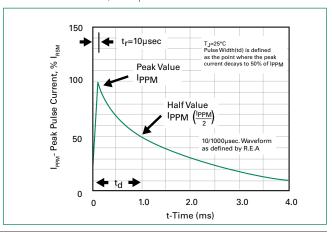
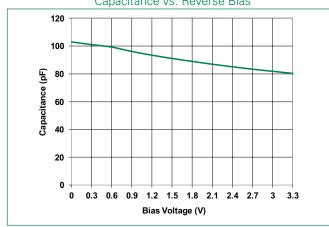
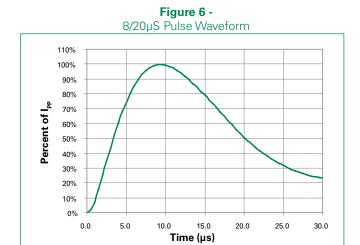




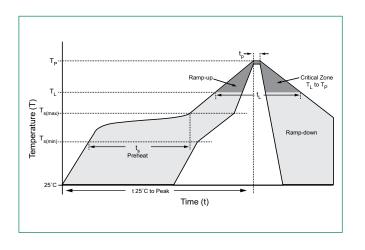
Figure 5 - Capacitance vs. Reverse Bias





Soldering Parameters

Reflow Cond	lition	Lead-free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 – 120 secs	
Average ram peak	p up rate (Liquidus Temp (T _L) to	3°C/second max	
T _{S(max)} to T _L - I	Ramp-up Rate	3°C/second max	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
	-Time (min to max) (t _L)	60 – 150 seconds	
Peak Temper	ature (T _P)	260+0/-5 °C	
Time within	5°C of actual peak Temperature (t _p)	30 seconds max	
Ramp-down	Rate	6°C/second max	
Time 25°C to	peak Temperature (T _p)	8 minutes max.	
Do not excee	ed	260°C	



Physical Specifications

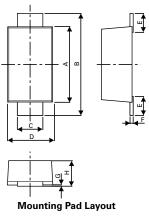
Case	SOD-123FL plastic over passivated junction
Polarity	Color band denotes cathode except bipolar
Terminal	Matte tin-plated leads, solderable per JESD22-B102

Environmental Specification

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, LEVEL 1
H3TRB	JESD22-A101
RSH	JESD22-A111

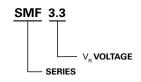


Dimensions - SOD-123FL Package



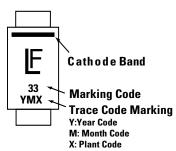
Mounting Pad Layout					
	1.6 (0.062)	1.3 (0.051)			
Ì	•	1			
			1.4 (0.055)		

Part Numbering System



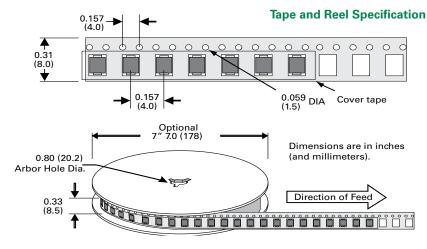
Millimeters Inches **Dimensions** Min Max Min Max 3.10 0.106 0.122 Α 2.70 В 3.50 3.90 0.138 0.154 С 0.85 1.05 0.033 0.041 D 1.70 2.00 0.067 0.079 Ε 0.43 0.83 0.017 0.033 F 0.10 0.25 0.004 0.010 G 0.00 0.10 0.000 0.004 Н 0.90 0.043 1.08 0.035

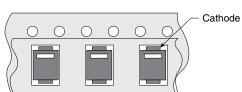
Part Marking System



Packaging Options

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMF3.3	SOD-123FL	3000	Tape & Reel – 8mm tape/7" reel	EIA RS-481





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